- Designed for Complementary Use with BDW63, BDW63A, BDW63B, BDW63C and BDW63D
- 60 W at 25°C Case Temperature
- 6 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 2 A

Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

| RATING | SYMBOL | VALUE | UNIT | |
|---|-------------------------------|------------------|------|---|
| | BDW64 | | -45 | |
| | BDW64A | | -60 | |
| Collector-base voltage (I _E = 0) | BDW64B | V_{CBO} | -80 | V |
| | BDW64C | | -100 | |
| | BDW64D | | -120 | |
| | BDW64 | | -45 | |
| | BDW64A | | -60 | |
| Collector-emitter voltage (I _B = 0) (see Note 1) | BDW64B | V_{CEO} | -80 | V |
| | BDW64C | | -100 | |
| | BDW64D | | -120 | |
| Emitter-base voltage | | V _{EBO} | -5 | V |
| Continuous collector current | I _C | -6 | Α | |
| Continuous base current | I _B | -0.1 | Α | |
| Continuous device dissipation at (or below) 25°C case temperature (see Note 2 | P _{tot} | 60 | W | |
| Continuous device dissipation at (or below) 25°C free air temperature (see Note | P _{tot} | 2 | W | |
| Unclamped inductive load energy (see Note 4) | ½LI _C ² | 50 | mJ | |
| Operating junction temperature range | T _j | -65 to +150 | °C | |
| Operating temperature range | T _{stg} | -65 to +150 | °C | |
| Operating free-air temperature range | T _A | -65 to +150 | °C | |

NOTES: 1. These values apply when the base-emitter diode is open circuited.

- 2. Derate linearly to 150°C case temperature at the rate of 0.48 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
- 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = -5 mA, R_{BE} = 100 Ω , $V_{BE(off)}$ = 0, R_S = 0.1 Ω , V_{CC} = -20 V.



BDW64, BDW64A, BDW64B, BDW64C, BDW64D PNP SILICON POWER DARLINGTONS

AUGUST 1978 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | | | MIN | TYP | MAX | UNIT |
|----------------------|--------------------------------------|--|--|----------------------------------|--|---------------------------|-----|--|------|
| V _{(BR)CEO} | Collector-emitter breakdown voltage | I _C = -30 mA | I _B = 0 | (see Note 5) | BDW64 BDW64A BDW64B BDW64C | -45 -60 -80 -100 | | | V |
| I _{CEO} | Collector-emitter cut-off current | $V_{CE} = -30 \text{ V}$ $V_{CE} = -30 \text{ V}$ $V_{CE} = -40 \text{ V}$ $V_{CE} = -50 \text{ V}$ $V_{CE} = -60 \text{ V}$ | $I_{B} = 0$ $I_{B} = 0$ $I_{B} = 0$ | | BDW64D BDW64 BDW64A BDW64B BDW64C BDW64D | -120 | | -0.5 -0.5 -0.5 -0.5 -0.5 | mA |
| I _{CBO} | Collector cut-off current | $V_{CB} = -45 \text{ V}$ $V_{CB} = -60 \text{ V}$ $V_{CB} = -80 \text{ V}$ $V_{CB} = -100 \text{ V}$ $V_{CB} = -120 \text{ V}$ | I _E = 0 I _E = 0 | $T_C = 150$ °C $T_C = 150$ °C | BDW64 BDW64A BDW64B BDW64C BDW64D BDW64 BDW64A BDW64A BDW64B BDW64C BDW64D | | | -0.2 -0.2 -0.2 -0.2 -0.2 -5 -5 -5 -5 | mA |
| I _{EBO} | Emitter cut-off current | V _{EB} = -5 V | | | | | | -2 | mA |
| h _{FE} | Forward current transfer ratio | $V_{CE} = -3 V$ $V_{CE} = -3 V$ | - | (see Notes 5 and 6) | | 750 100 | | 20000 | |
| $V_{\text{BE(on)}}$ | Base-emitter voltage | V _{CE} = -3 V | - | (see Notes 5 and 6) | | | | -2.5 | V |
| V _{CE(sat)} | Collector-emitter saturation voltage | $I_B = -12 \text{ mA}$ $I_B = -60 \text{ mA}$ | - | (see Notes 5 and 6) | | | | -2.5 -4 | V |
| V _{EC} | Parallel diode forward voltage | I _E = -6 A | I _B = 0 | | | | | -3.5 | V |

NOTES: 5. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

| PARAMETER | MIN | TYP | MAX | UNIT |
|--|-----|-----|------|------|
| R _{0JC} Junction to case thermal resistance | | | 2.08 | °C/W |
| R _{0JA} Junction to free air thermal resistance | | | 62.5 | °C/W |

resistive-load-switching characteristics at 25°C case temperature

| | PARAMETER | TEST CONDITIONS † | | | MIN | TYP | MAX | UNIT |
|------------------|---------------|-----------------------|------------------------------|------------------------------|-----|-----|-----|------|
| t _{on} | Turn-on time | I _C = -3 A | $I_{B(on)} = -12 \text{ mA}$ | $I_{B(off)} = 12 \text{ mA}$ | | 1 | | μs |
| t _{off} | Turn-off time | $V_{BE(off)} = 4.5 V$ | $R_L = 10 \Omega$ | $t_p = 20 \mu s, dc \le 2\%$ | | 5 | | μs |

[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

PRODUCT INFORMATION

^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN COLLECTOR CURRENT TCS125AD 40000 $T_c = -40^{\circ}C$ 25°C $T_{\rm C} = 100^{\circ}{\rm C}$ h_{FE} - Typical DC Current Gain 10000 1000 -3 V = 300 µs, duty cycle < 2% 100 -0-5 -1-0 -10 Ic - Collector Current - A

Figure 1.

COLLECTOR-EMITTER SATURATION VOLTAGE

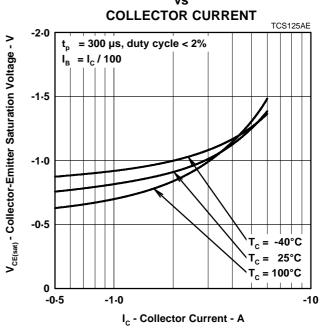


Figure 2.

BASE-EMITTER SATURATION VOLTAGE

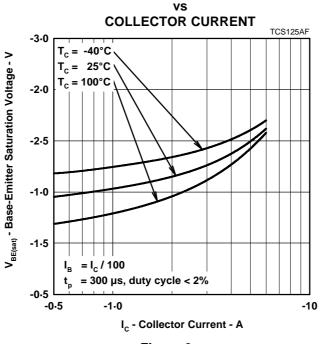
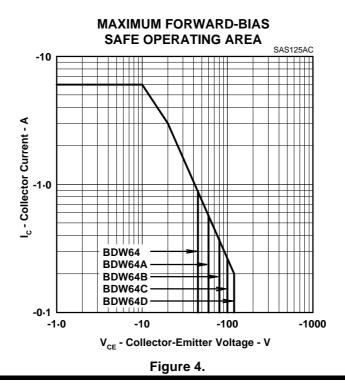


Figure 3.

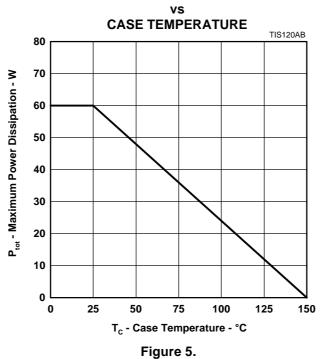


MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION



PRODUCT INFORMATION

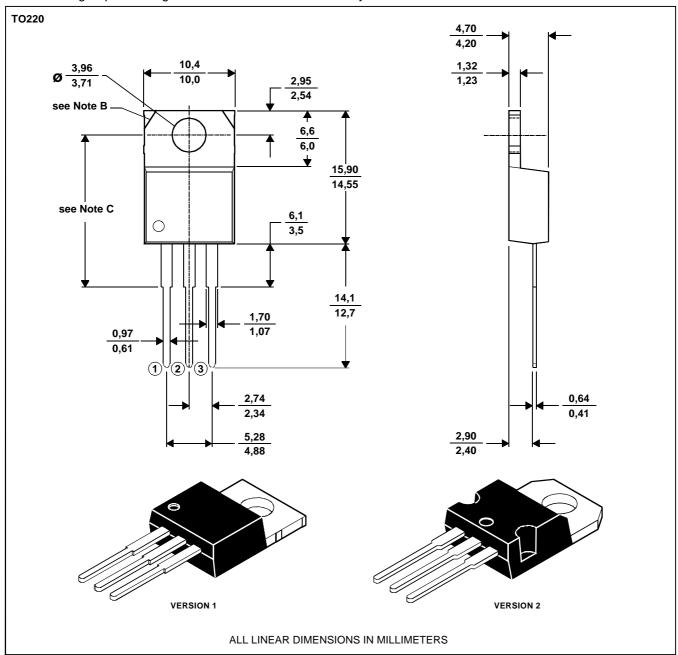
AUGUST 1978 - REVISED MARCH 1997

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

- B. Mounting tab corner profile according to package version.
- C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm.

MDXXBE

PRODUCT INFORMATION

BDW64, BDW64A, BDW64B, BDW64C, BDW64D PNP SILICON POWER DARLINGTONS

AUGUST 1978 - REVISED MARCH 1997

IMPORTANT NOTICE

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 1997, Power Innovations Limited